

WHAT IS CLAIMED IS:

1. A mounting structure of a semiconductor device mounted on a mounting substrate, comprising:
 - 5 a semiconductor device having a bump electrode which has an acute tip on top,
 - a mounting substrate on which said semiconductor device is mounted, and
 - a conductor pattern formed on said mounting substrate, wherein said acute tip is gradually depressed on said conductor pattern of said mounting substrate.
- 10 2. A mounting structure of a semiconductor device mounted on a mounting substrate as claimed in Claim 1, wherein said acute tip of the bump electrode is treated with a leveling process as to form a small flat surface before depressed on said conductor pattern of the mounting substrate.
- 15 3. A mounting structure of a semiconductor device mounted on a mounting substrate as claimed in Claim 2, wherein heat is added to said bump electrode of the semiconductor device so that said bump electrode is transformed during depression of the bump electrode to the conductor pattern of the mounting substrate.
- 20 4. A mounting structure of a semiconductor device mounted on a mounting substrate as claimed in Claim 3, wherein said mounting substrate is a printed circuit board and said bump electrode is depressed on the conductor pattern formed on the printed circuit board.
- 25 5. A mounting structure of a semiconductor device mounted on a mounting substrate as claimed in Claim 4, wherein said semiconductor device has an electrode pad and said bump electrode is formed on this electrode.
- 30 6. A mounting structure of a semiconductor device mounted on a mounting substrate as claimed in Claim 1, wherein said acute tip of the bump electrode has a shape of a cone.
7. A process of mounting a semiconductor device on a mounting substrate, said process comprising the steps of,